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United States Patent [19]

Cooper

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[54] ELECTRONIC CIRCUIT HOUSING

[75] Inventor: David Cooper, Seattle, Wash.

[73] Assignee: Eldec Corporation, Lynnwood,

Wash.

[**] Term: 14 Years

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Related U.S. Application Data

[62]	Division of Ser. No. 954	,930, Sep. 29, 19	992.
[52]	U.S. Cl	*******	D13/110
	Field of Search		
	336/90, 92, 200;	363/15, 95; 3	07/150, 151
	174/52.1, 52	.2; D13/110, 1	23, 124, 184

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Primary Examiner—Wallace R. Burke
Assistant Examiner—Joel Sincavage
Attorney, Agent, or Firm—Christensen, O'Connor,
Johnson & Kindness

[57] CLAIM

The ornamental design for an electronic circuit housing, as shown and described.

DESCRIPTION

FIG. 1 is a top front perspective view of an electronic circuit housing showing my new design;

FIG. 2 is a bottom plan view thereof;

FIG. 3 is an end elevational view thereof taken from the left of FIG. 2;

FIG. 4 is a rear elevational view thereof;

FIG. 5 is an end elevational view thereof taken from the right of FIG. 2;

FIG. 6 is a top front perspective view of a second embodiment thereof;

FIG. 7 is a bottom plan view of the second embodiment thereof;

FIG. 8 is an end elevational view of the second embodiment thereof taken from the left of FIG. 7;

FIG. 9 is a rear elevational view of the second embodiment thereof;

FIG. 10 is an end elevational view of the second embodiment thereof taken from the right of FIG. 7;

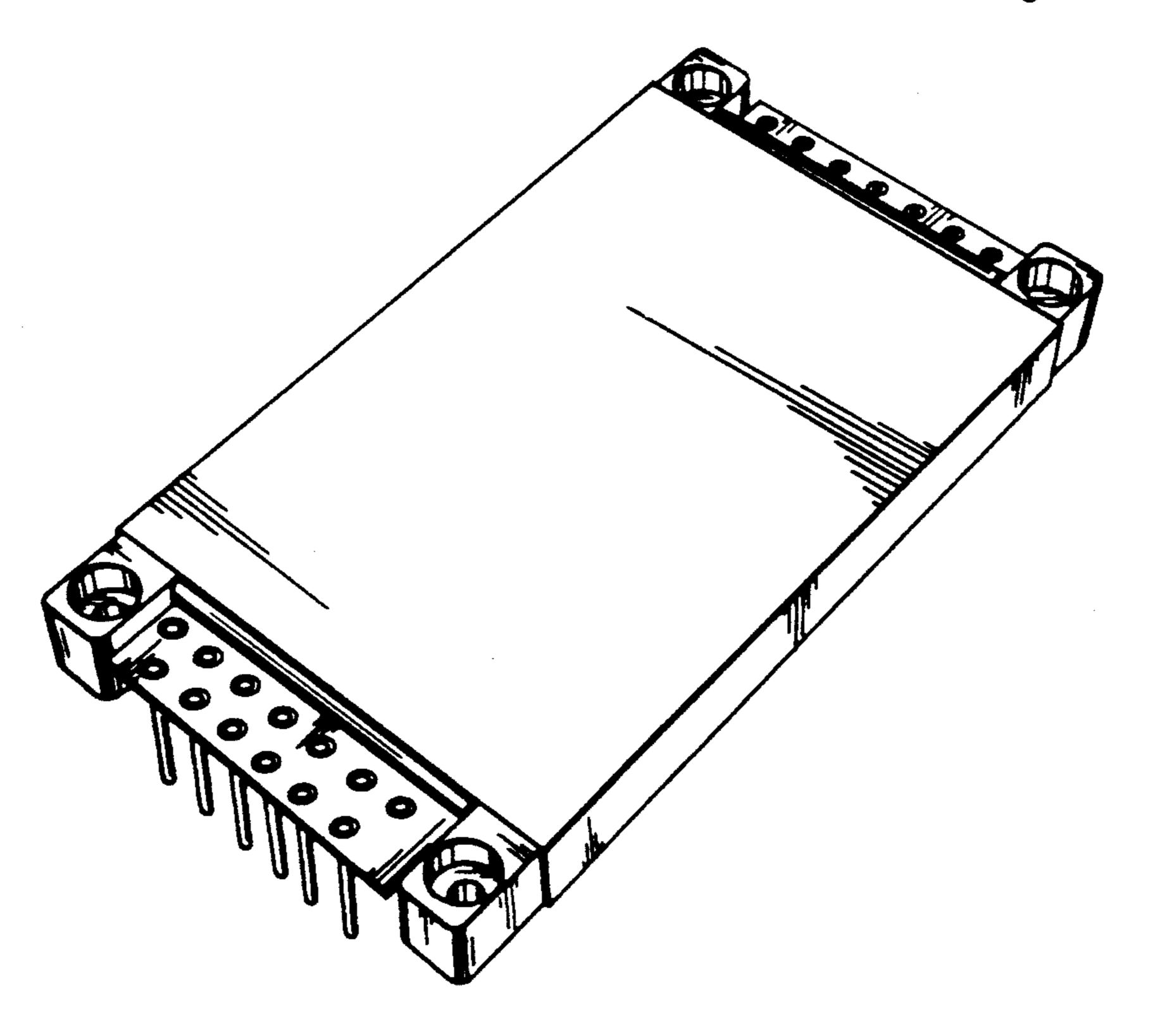
FIG. 11 is a top front perspective view of a third embodiment thereof;

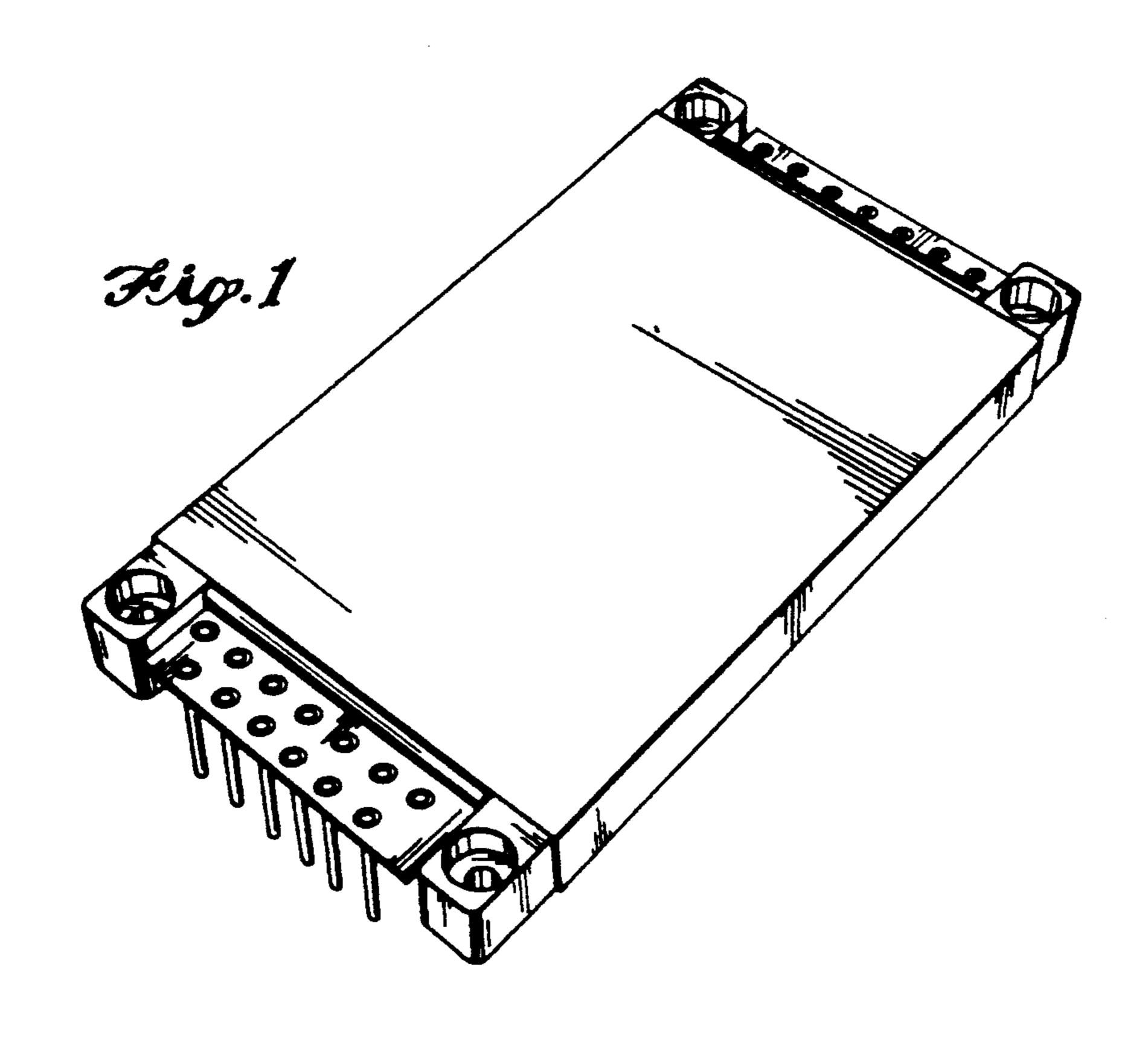
FIG. 12 is a bottom plan view of the third embodiment thereof;

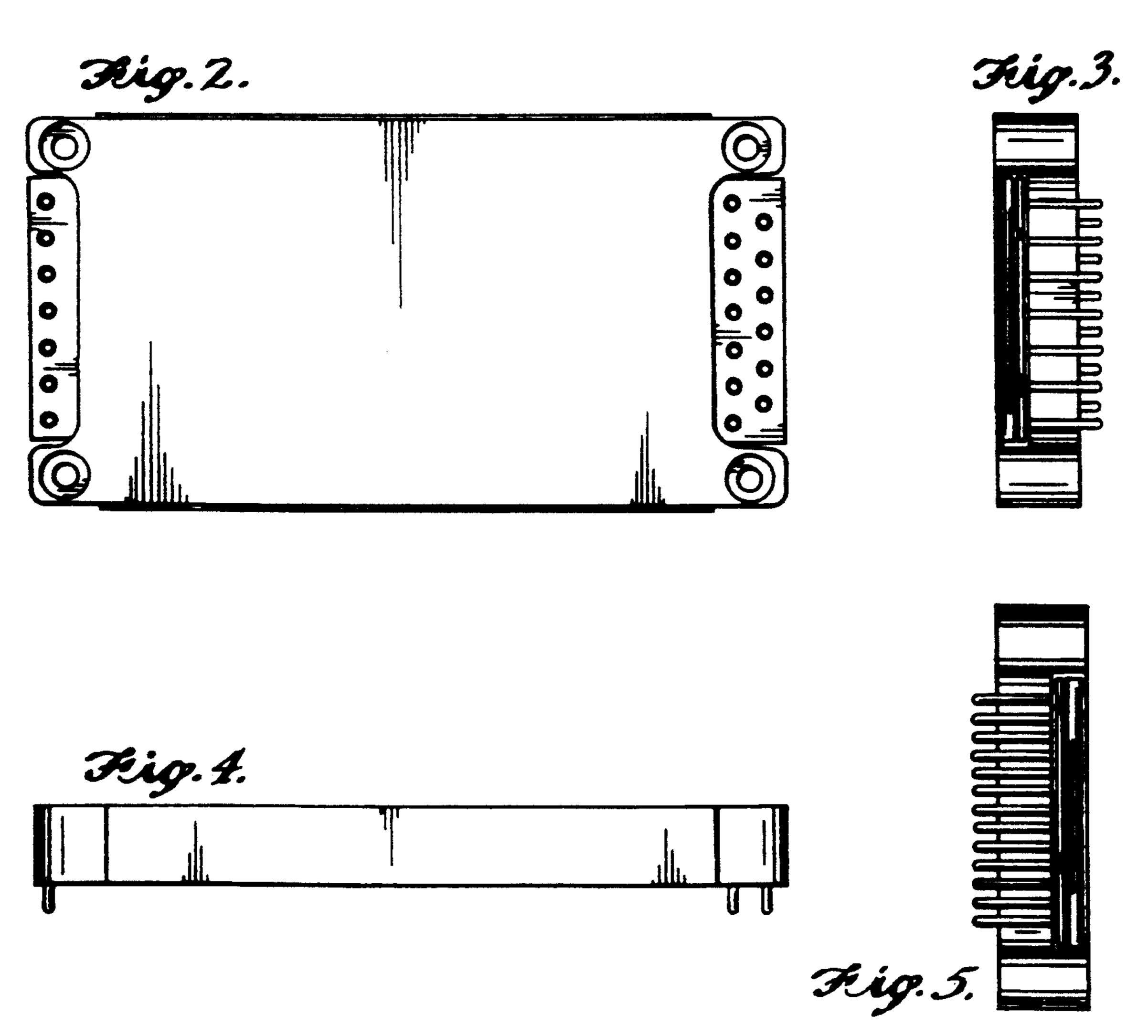
FIG. 13 is an end elevational view of the third embodiment thereof taken from the left of FIG. 12;

FIG. 14 is a rear elevational view of the third embodiment thereof; and,

FIG. 15 is an end elevational view of the third embodiment thereof taken from the right of FIG. 12.







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